

# PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	<b>CORRECTIVE ASSIGNMENT</b>												
<b>NATURE OF CONVEYANCE:</b>	Corrective Assignment to correct the name of the Inventor from Meng Fen Cai to Meng Feng Tsai previously recorded on Reel 024039 Frame 0886. Assignor(s) hereby confirms the name of the Inventor Meng Feng Tsai.												
<b>CONVEYING PARTY DATA</b>													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Meng Feng Tsai</td> <td>06/21/2011</td> </tr> <tr> <td>Lily Jiang</td> <td>12/18/2009</td> </tr> <tr> <td>Jian Guang Chang</td> <td>01/06/2010</td> </tr> </tbody> </table>		Name	Execution Date	Meng Feng Tsai	06/21/2011	Lily Jiang	12/18/2009	Jian Guang Chang	01/06/2010				
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<b>RECEIVING PARTY DATA</b>													
<table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 20%;"><b>Name:</b></td> <td>Semiconductor Manufacturing International (Shanghai) Corporation</td> </tr> <tr> <td><b>Street Address:</b></td> <td>18 Zhang Jiang Road</td> </tr> <tr> <td><b>Internal Address:</b></td> <td>Pudong New Area</td> </tr> <tr> <td><b>City:</b></td> <td>Shanghai</td> </tr> <tr> <td><b>State/Country:</b></td> <td>CHINA</td> </tr> <tr> <td><b>Postal Code:</b></td> <td>201203</td> </tr> </table>		<b>Name:</b>	Semiconductor Manufacturing International (Shanghai) Corporation	<b>Street Address:</b>	18 Zhang Jiang Road	<b>Internal Address:</b>	Pudong New Area	<b>City:</b>	Shanghai	<b>State/Country:</b>	CHINA	<b>Postal Code:</b>	201203
<b>Name:</b>	Semiconductor Manufacturing International (Shanghai) Corporation												
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<b>CORRESPONDENCE DATA</b>													
<p>Fax Number: (650)326-2422  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 415-576-0200        Email: mtejera@kilpatricktownsend.com        Correspondent Name: KILPATRICK TOWNSEND AND STOCKTON LLP        Address Line 1: Two Embarcadero Center        Address Line 2: Eighth Floor        Address Line 4: San Francisco, CALIFORNIA 94111</p>													
<b>ATTORNEY DOCKET NUMBER:</b>	87720-722356 (015710US)												
<b>NAME OF SUBMITTER:</b>	Dah Bin Kao												

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**PATENT**  
**REEL: 026524 FRAME: 0557**

**Total Attachments: 13**

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Attorney Docket No.: 87720-722356

(IP Family 015710US)

Client Reference No. 2004-00267-SH-US-DA1

## ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, Lily Jiang of 18 Zhang Jiang Rd., Pudong New Area, Shanghai 201203; People's Republic of China, Meng Fen Cai of 18 Zhang Jiang Rd., Pudong New Area, Shanghai 201203; People's Republic of China and Jian Guang Chang of 18 Zhang Jiang Rd., Pudong New Area, Shanghai 201203, People's Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: A Method and Structure for Performing a Chemical Mechanical Polishing Process

Filing Date: December 29, 2009

Application No.: 12/647,362 ; and

WHEREAS, Semiconductor Manufacturing International (Shanghai) Corporation, a corporation of People's Republic of China, located at 18 Zhang Jiang Rd, Pudong New Area, Shanghai, 201203 People's Republic of China, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: \_\_\_\_\_

\_\_\_\_\_  
Lily Jiang

Dated: 2011-6-21 \_\_\_\_\_

\_\_\_\_\_  
Meng Feng Tsai  
Meng Feng Tsai

PATENT

REEL: 026524 FRAME: 0559

Assignment

Attorney Docket No.: 021653-015710US

Page 2

Dated: \_\_\_\_\_

\_\_\_\_\_  
Jian Guang Chang

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## PATENT ASSIGNMENT

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03/07/2010  
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ATTORNEY DOCKET NUMBER:	021653-015710US										
NAME OF SUBMITTER:	Ardeshir Tabibi										
Total Attachments: 2 source=021653-015710US EXECUTED ASSIGNMENT#page1.tif source=021653-015710US EXECUTED ASSIGNMENT#page2.tif											

CH 12647362 \$40.00

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For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

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IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: 2009/12/18

Lily Jiang 蒋莉  
Lily Jiang

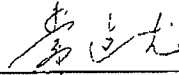
Dated: 2010-1-7

Meng Fen Cai 蔡峰  
Meng Fen Cai

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Attorney Docket No.: 021653-015710US  
Page 2

Dated: 2010.01.06

61828176 v1



Jian Guang Chang

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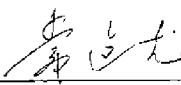
Meng Fen Cai 蔡芬  
Meng Fen Cai



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